



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Drill, C. et al.

Serial No. : 08/824,633 Group Art Unit : 3724

Filed : 03/27/97 Examiner : Rachuba, M.

For : A CUSTOMIZED POLISHING PAD FOR SELECTIVE PROCESS
PERFORMANCE DURING CHEMICAL MECHANICAL
POLISHING

10/21/1999
Hg / Super B
Hg / 10/21/1999
Hg / Hart

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents & Trademarks
Washington, D.C. 20231

RECEIVED

NOV 30 1999

Group 3700

Sir:

In response to the Office Action mailed 07/21/99, please amend the
above-referenced Application as follows:

IN THE CLAIMS

Please amend the claims as shown below:

1. (Amended) A customized polishing pad adapted for use in a wafer
polishing machine, said customized polishing pad comprising:
a polishing pad adapted for use in a wafer polishing machine;
a polishing surface of an overlying layer included in said polishing pad,
said overlying layer being a uniform homogenous layer across the area of said
polishing surface, said polishing surface adapted to frictionally contact a wafer
in said wafer polishing machine;
said polishing surface having a first region [integral with said polishing
surface, said first region adapted to frictionally contact said wafer];